

CLAIMS:

1. An abrasive agent comprising abrasive particles, said particles being in the form of a composite material comprising more than one metal oxide.
2. An abrasive agent according to claim 1, wherein said abrasive particles are in the form of a composite material made of at least two metal oxides.
3. An abrasive agent according to claim 2, wherein said composite material comprises SiO_2 and Al_2O_3 .
4. An abrasive agent comprising metal oxide abrasive particles, said particles being coated at least partially with an extraneous metal or metal bearing layer.
5. An abrasive agent according to claim 4, wherein said abrasive particles are further coated at least partially with a polymer layer.
6. A chemical mechanical polishing (CMP) composition comprising an abrasive agent according to claim 1.
7. A chemical mechanical polishing (CMP) composition comprising an abrasive agent according to claim 4.
8. The CMP composition of claim 7 wherein the metallic or metal bearing layer include metals or metalloids at zero valence state, metal oxides, metal hydroxides, water-insoluble metal compounds, as well as mixtures thereof.

9. The CMP composition of claim 8 wherein the metal-bearing layer comprises at least one metal selected from the group consisting of Cu, Ti, Fe, Sn, Pb, Ta, Mo, Wo and Nb.
10. The CMP composition of claim 8 wherein the metal-bearing coating is a metal oxide.
11. A fixed abrasive CMP pad comprising abrasive particles according to claim 1.
12. A fixed abrasive CMP pad comprising abrasive particles according to claim 4.
13. A fixed abrasive CMP pad comprising abrasive particles according to claim 4, wherein said particles are completely covered with a metal bearing coating.
14. A CMP slurry comprising a CMP composition according to claim 6.
15. A CMP slurry comprising a CMP composition according to claim 7.
16. A CMP slurry comprising a CMP composition according to claim 7, wherein said abrasive particles are completely covered with a metal bearing coating.
17. A method of manufacturing an integrated circuit comprising using a composition according to claim 6.
18. A method of manufacturing an integrated circuit comprising using a composition according to claim 7.

19. An abrasive particle that is a single composite of at least two metal oxides.
20. An abrasive agent comprising abrasive particles, said particles being in the form of a composite material comprising more than one metal oxide and being coated at least partially with an extraneous metal or metal bearing layer.
21. A CMP slurry composition comprising at least one metal bearing colloid.
22. A CMP slurry composition according to claim 1 comprising at least one metal bearing colloid.